



GP1608X08-B30

SMD Type Green Emitter

Features

- Small double-end package
- X axis Viewing Angle = $\pm 65^\circ$
- High reliability
- Ultra bright Green
- RoHS compliance

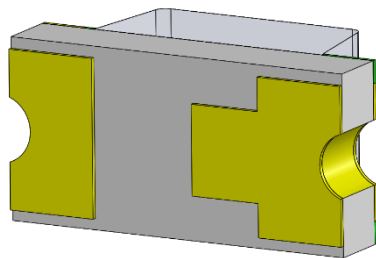
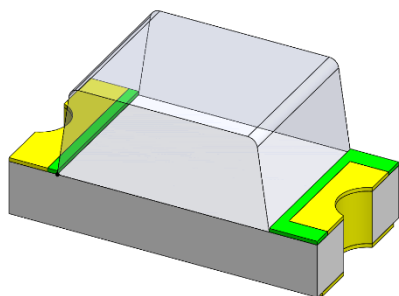
Applications

- Green sensor

Description

The GP1608X08-B30 is an InGaN Green LED housed in a miniature SMD package. The device has a dominant wavelength of 525nm LED spectrally matched with phototransistor or photodiode.

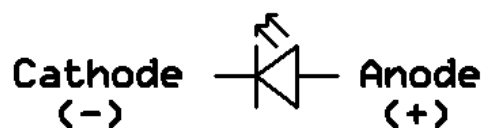
Package Outline



Cathode

Anode

Schematic





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Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
I _F	Continuous Forward Current	20	mA	
I _{FP}	Peak Forward Current	0.1	A	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
P _D	Power Dissipation at(or below) 25°C Free Air Temperature	68	mW	

Electro-Optical Characteristics *TA = 25°C (unless otherwise specified)*

Optical Characteristics

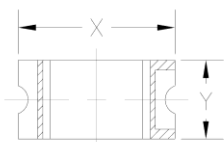
Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _v	Luminous Intensity	I _F =20mA	500	1100	-	mcd	
λ _p	Peak Wavelength	I _F =20mA	-	520	-	nm	
λ _d	Dominant Wavelength	I _F =20mA	515	525	535	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	30	-	nm	
θ _{1/2}	Angle of Half Intensity (X axis)	I _F =20mA	-	±65	-	deg	3
	Angle of Half Intensity (Y axis)		-	±70	-		

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.9	2.6	3.4	V	
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

1. I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 10%.
2. Soldering time ≤ 5 seconds.
3. Test Condition :

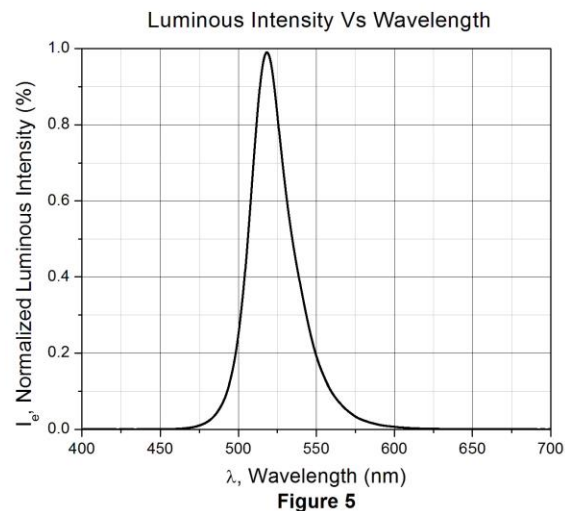
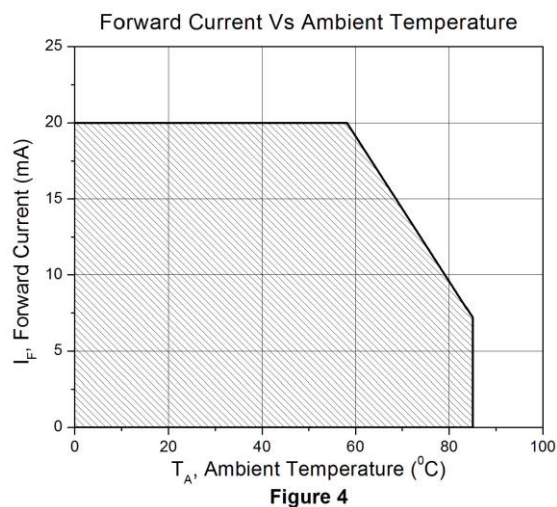
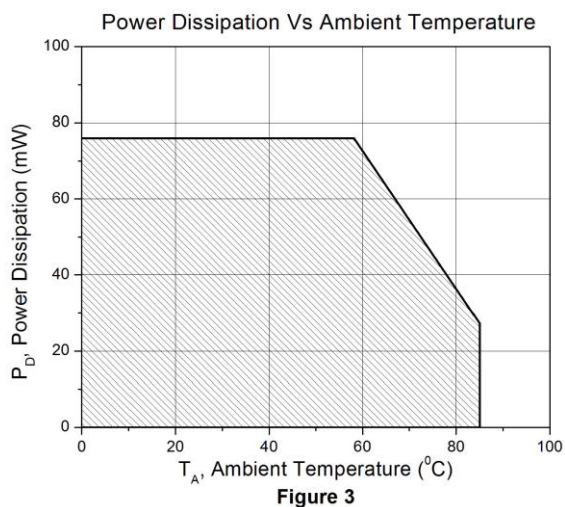
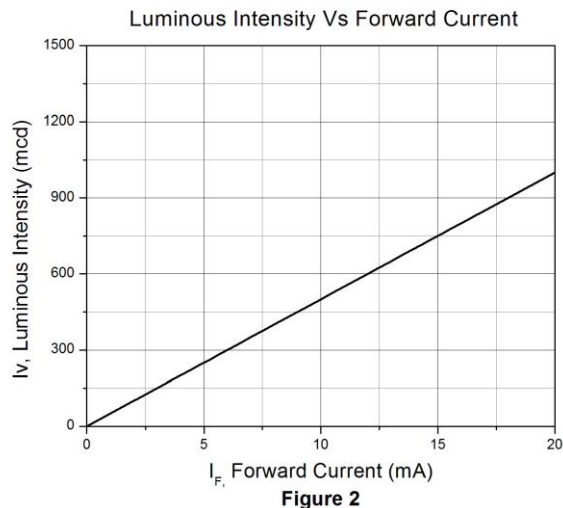
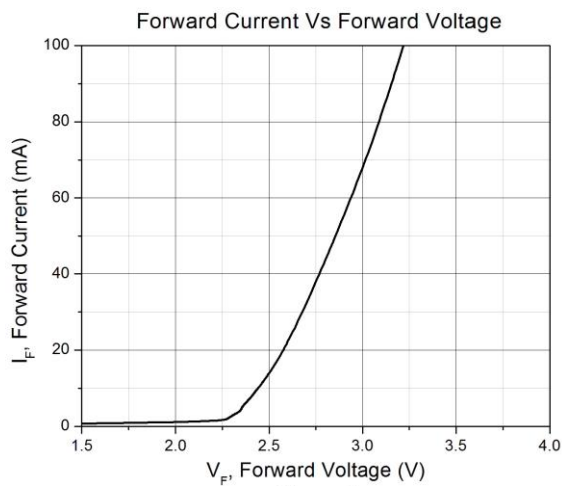




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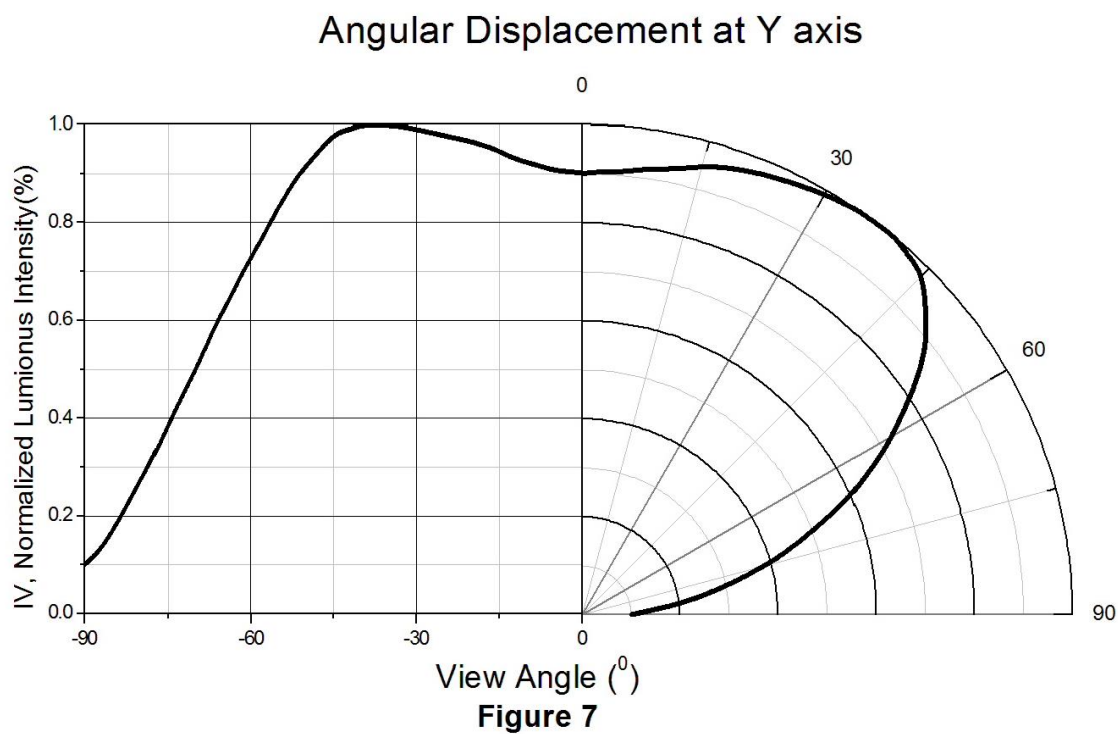
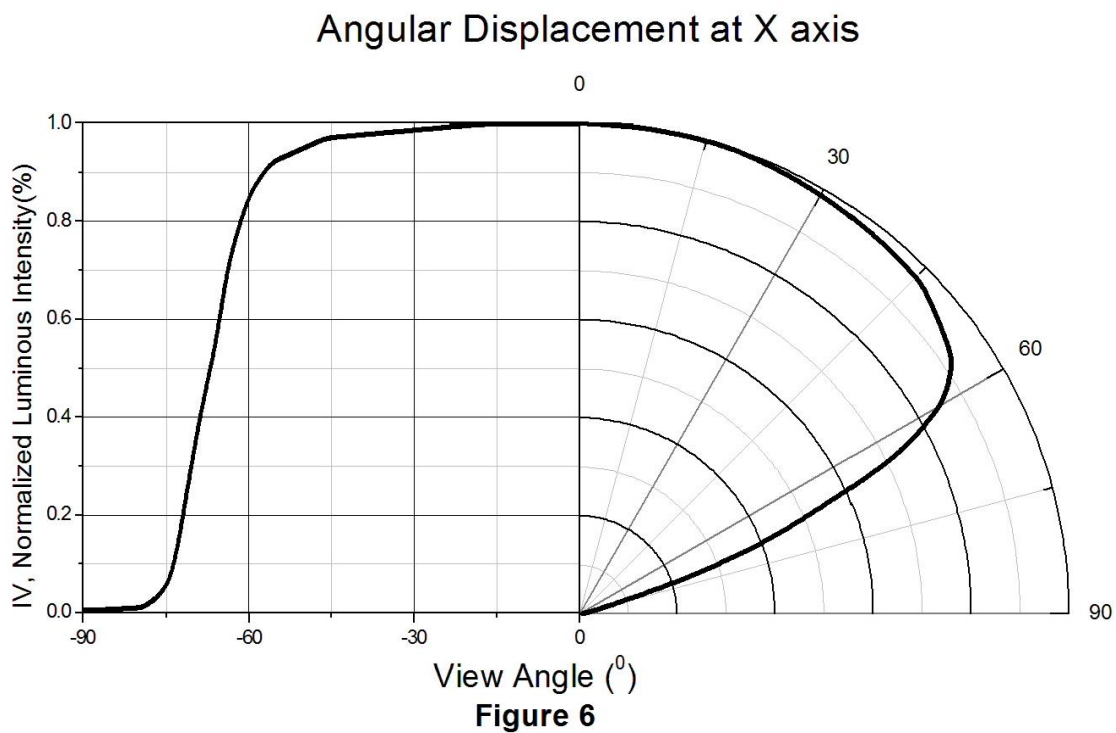
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Typical Characteristic Curves





Typical Characteristic Curves

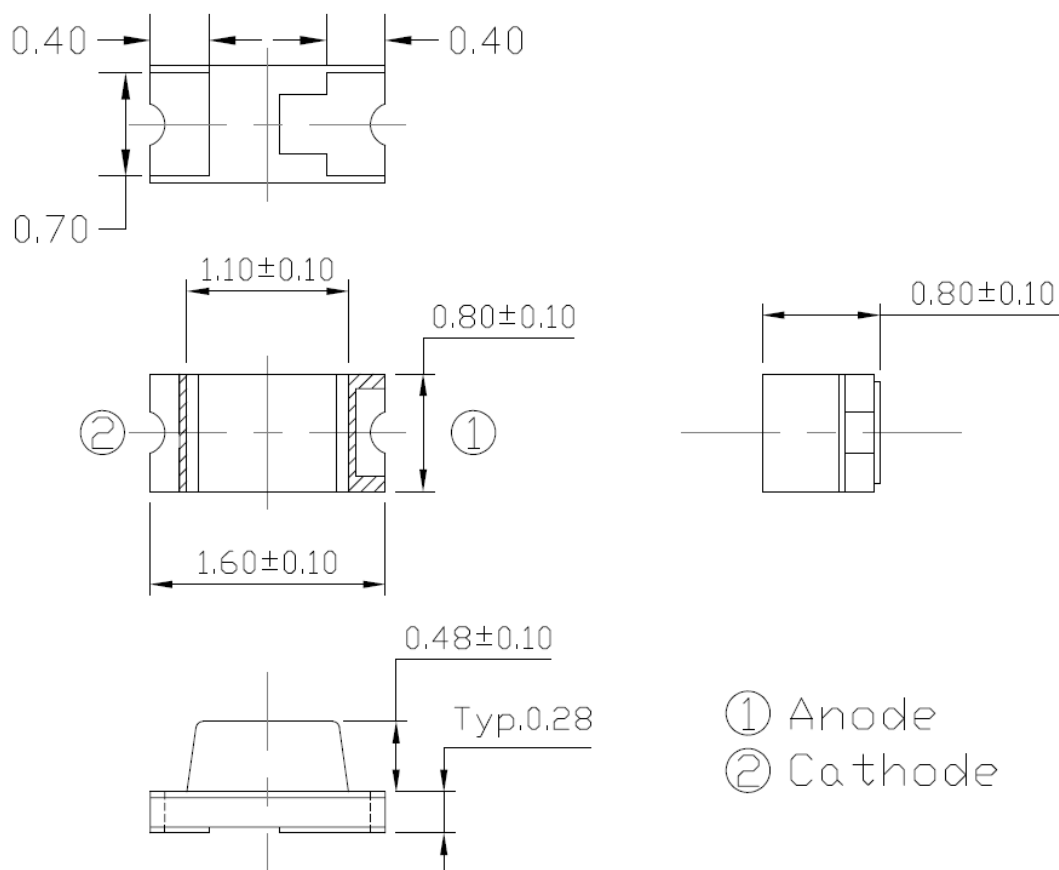




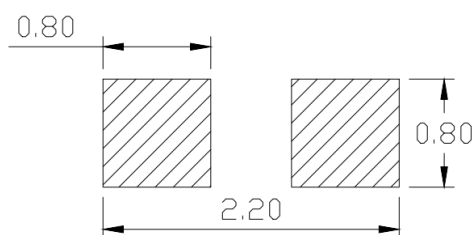
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Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



Ordering Information

Part Number	Description	Quantity
GP1608X08-B30	Tape & Reel	4000 pcs

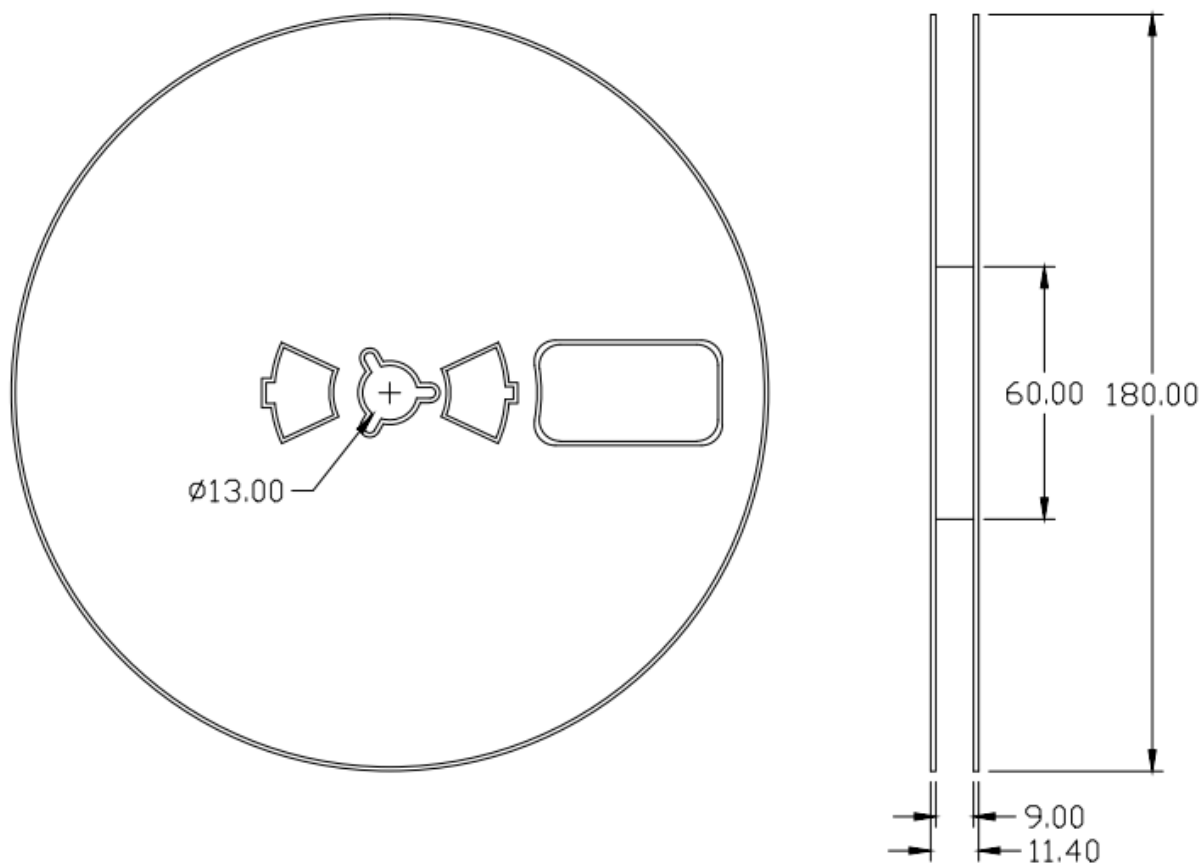


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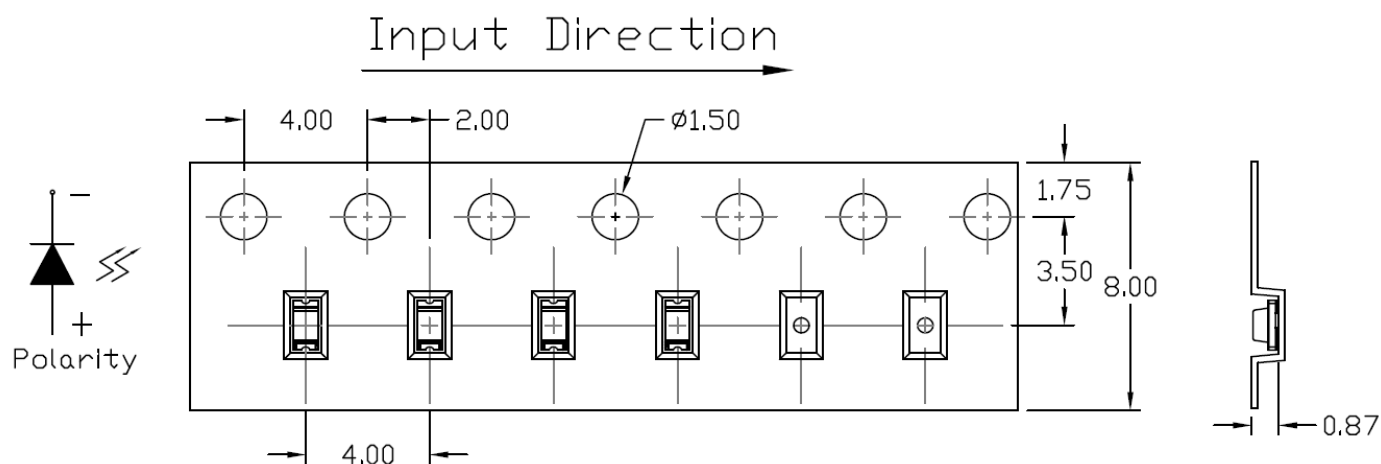
Reel Dimension

All dimensions are in mm, unless otherwise stated



Tape Dimension

All dimensions are in mm, unless otherwise stated





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Label Form Specification

CT Micro
International Corporation

MADE IN CHINA

Part no.: XXXXXXXXX
Serial no.: XX000XX
Lot no.: XXXXXXXXX
Q'ty: XXXX pcs
Date Code: 20XXXXX

Bin Code: X

RoHS

Part no: CTM Production Number
Serial no: Production Number
Lot no: Lot number
Q'ty: Packing Quantity
Date Code: Manufacture Date
Bin Code: Iv Ranks
MADE IN CHINA: Production Place

Storage Condition

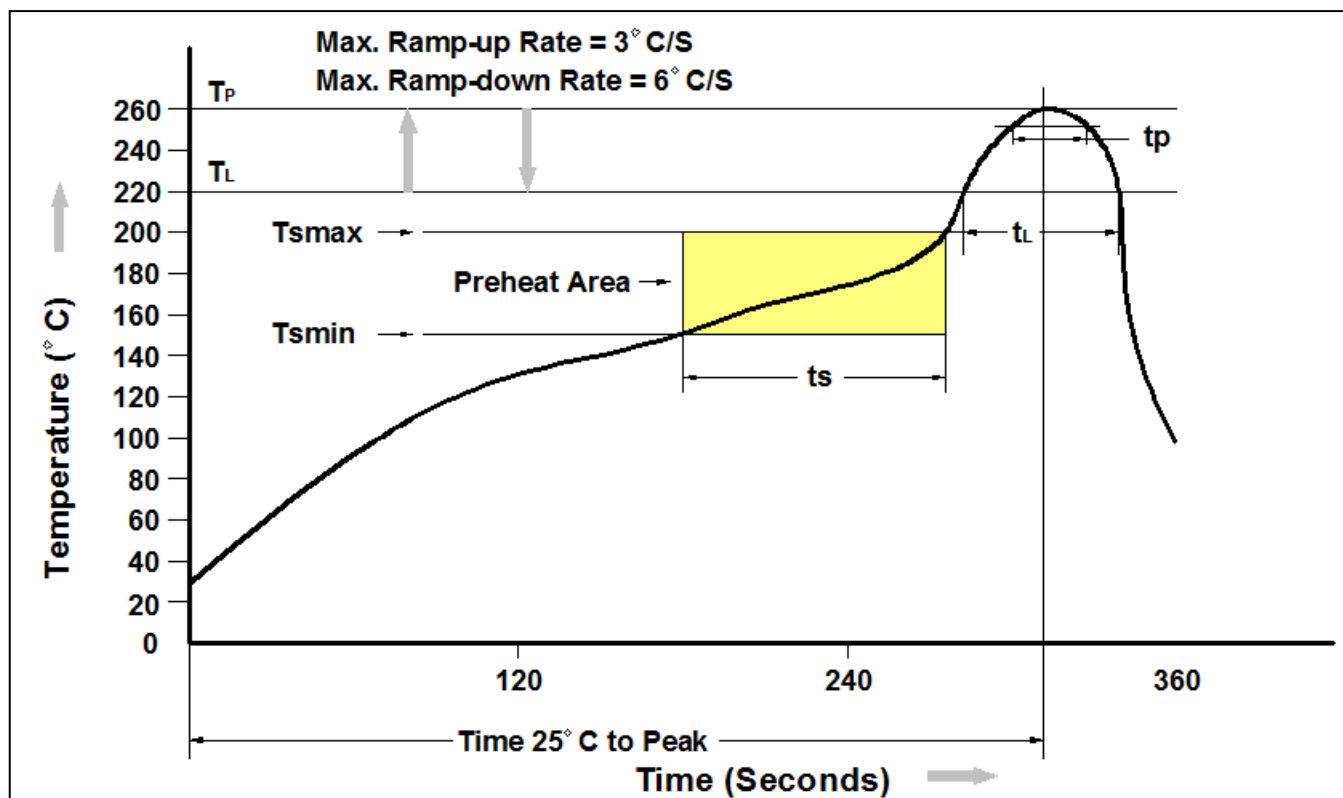
1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



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Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tssmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tssmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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